

1. Part Numbering System):

<u>CR</u>	<u>03</u>	<u>J</u>	<u>A</u>	<u>10K</u>
<p><u>Series Name</u> Chip Resistor: CR: Thick Film chip resistors</p>	<p><u>Type</u> Inch (mm) A8-1218(3248) 0A-2010(5025) 12-2512(6432)</p>	<p><u>Tolerance</u> B= ± 0.1% D= ± 0.5% F= ± 1% J= ± 5 % P : Jumper</p>	<p><u>Package</u> A=4Kpcs/7”Reel B=5Kpcs/7”Reel Z=3Kpcs/7”Reel</p>	<p><u>Resistance</u> 1R2=1.2Ω 10K=10KΩ 10K5=10.5KΩ 100K=100KΩ 1M2=1.2MΩ</p>

2. FEATURE

- High power rating and compact size
- High reliability and stability
- Reduced size of final equipment
- RoHS compliant and Lead free products

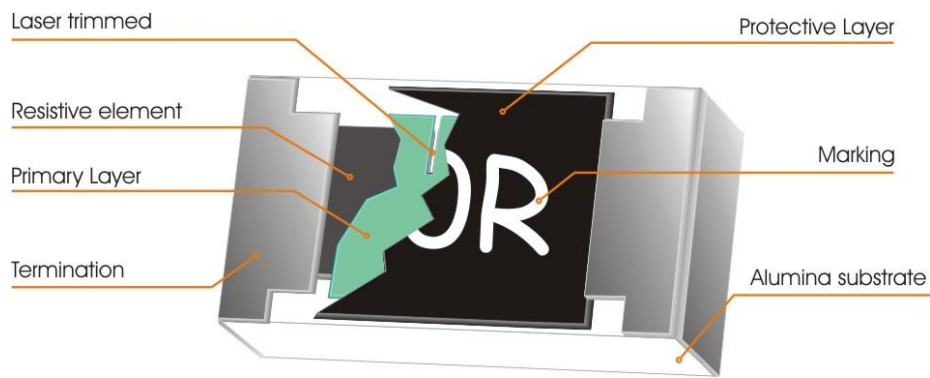
3. APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

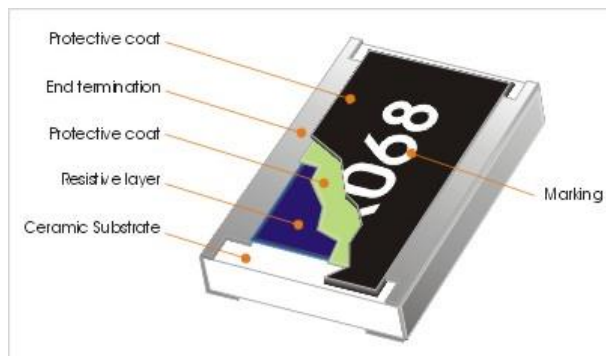
4.DESCRPTION

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to nominated value within tolerance which controlled by laser trimming of this resistive layer.

The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is Tin (lead free) alloy.



2512, 2010 Chip-R



1218 Chip-R

5. QUICK REFERENCE DATA

Item	General Specification		
Series No.	CRA8	CR0A	CR12
Size code	1218	2010	2512
Resistance Tolerance	±5% (E24); ±0.5%, ±0.1% , ±1% (E24+E96)		
Resistance Range	1Ω ~ 10MΩ, Jumper (0Ω)		
TCR (ppm/°C) : 10Ω< Rn ≤ 10MΩ 1Ω≤ Rn ≤ 10Ω	± 100 ppm/°C	± 100 ppm/°C	± 100 ppm/°C
	± 200 ppm/°C	± 200 ppm/°C	± 200 ppm/°C
Max. dissipation at T _{amb} =70°C	1W	0.75 W	1W
Max. Operation Voltage (DC or RMS)	200V	200V	250V
Max. Overload Voltage (DC or RMS)	400V	400V	500V
Operation temperature	-55 ~ +155°C		
Storage temperature	5 ~ 40°C		

Test conditions for jumper (0 ohm)

Type	CRA8	CR0A	CR12
Power Rating At 70C	1 W	3/4 W	1 W
Resistance	Max. 50mR	Max. 50mR	Max. 50mR
Rated Current	4.5 A	3.8 A	4.5 A
Peak Current	11 A	9 A	11 A
Operating Temperature	-55C ~ 155C	-55C ~ 155C	-55C ~ 155C

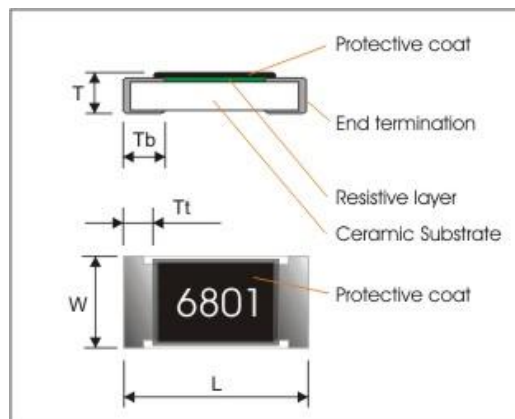
Note :

1. This is the maximum voltage that may be continuously supplied to the resistor element, see “IEC publication 60115-8”
2. Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by

$$RCWV = \sqrt{\text{Rated Power} \times \text{Resistance Value}}$$
 or Max. RCWV listed above, whichever is lower.
3. Max. Operation Current : So called RCWC (Rated Continuous Working Current) is determined by
4.
$$RCWC = \sqrt{\text{Rated Power} / \text{Resistance Value}}$$

6.MECHANICAL DATA(unit :mm)

TYPE	CRA8	CR0A	CR12
L	3.05±0.15	5.00±0.20	6.40±0.20
W	4.60±0.20	2.50±0.20	3.20±0.20
T	0.55±0.10	0.55±0.10	0.60±0.10
Tt	0.45±0.25	0.65±0.25	0.65±0.25
Tb	0.50±0.25	0.60±0.25	0.90±0.25



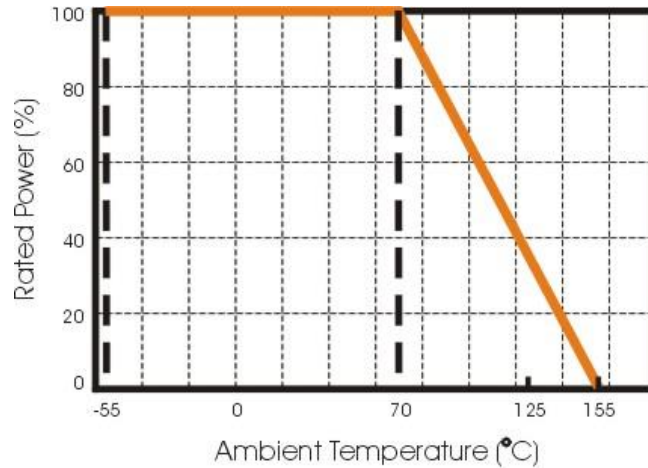
7.FUNCTIONAL DESCRIPTION

7.1 Product characterization

Standard values of nominal resistance are taken from the E24&E96 series for resistors with a tolerance of $\pm 0.1\%$, $\pm 0.5\%$, $\pm 1\%$, $\pm 5\%$, The values of the E24/E96 series are in accordance with “IEC publication 60063”

7.2 Derating curve

The power that the resistor can dissipate depends on the operating temperature; see the figure below:



Maximum dissipation in percentage of rated power as a function of the ambient temperature.

7.3 SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in below.

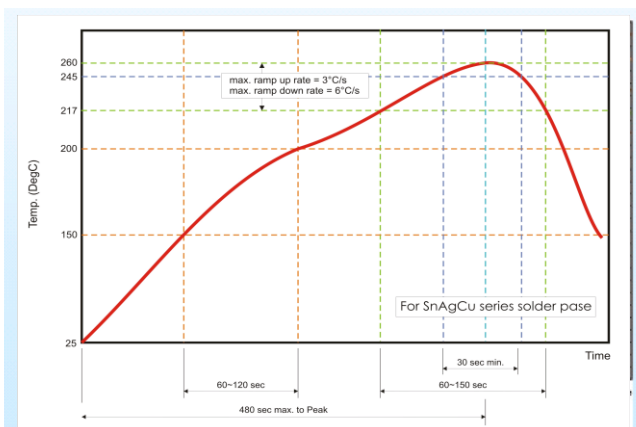


Fig. 1 Recommended IR reflow soldering profile for SMT process with SnAgCu series solder paste.

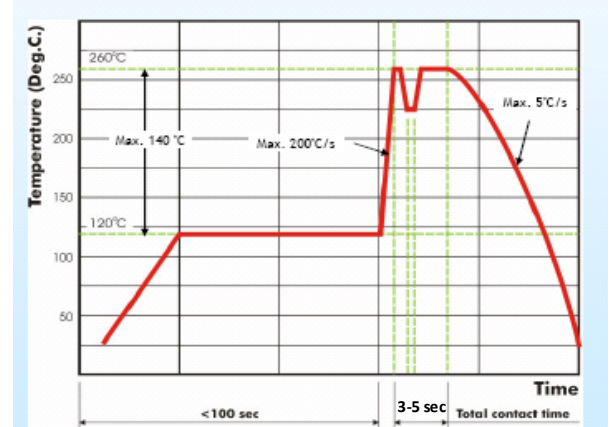


Fig. 2 Recommended wave soldering profile for SMT process with SnAgCu series solder.

7.4 TEST AND REQUIREMENTS(JISC 52011 : 199)

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category **LCT/UCT/56** (rated temperature range : Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS.

The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied :

Temperature: 15 °C to 35 °C.

Relative humidity: 45% to 75%.

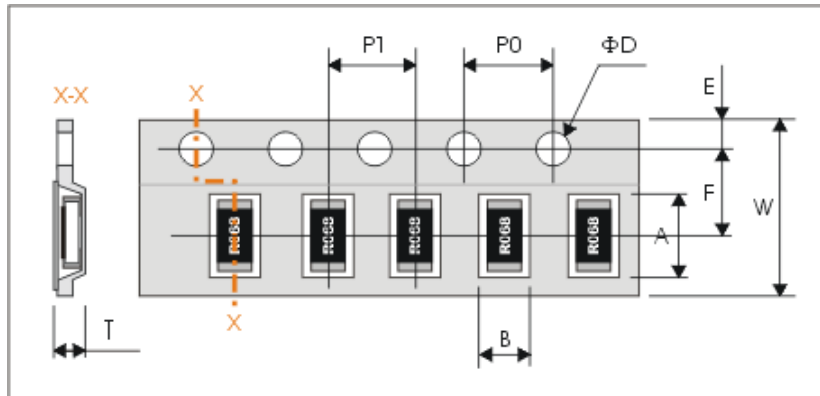
Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar).

All soldering tests are performed with mildly activated flux.

TEST	PROCEDURE	REQUIREMENT
DC resistance Clause 4.5	DC resistance values measured at the test voltages specified below : <10Ω@0.1V, <100Ω@0.3V, <1KΩ@1.0V, <10KΩ@3V, <100KΩ@10V, <1MΩ@25V, <10MΩ@30V	Within the specified tolerance
Temperature Coefficient of Resistance(T.C.R) Clause 4.8	Natural resistance change per change in degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$ $t_1 : 20^\circ\text{C}+5^\circ\text{C}-1^\circ\text{C}$ R ₁ : Resistance at reference temperature R ₂ : Resistance at test temperature	Refer to "QUICK REFERENCE DATA"
Short time overload (S.T.O.L) Clause 4.13	Permanent resistance change after a 5second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less.	ΔR/R max. ±(2%+0.1Ω)
Resistance to soldering heat(R.S.H) Clause 4.18	Un-mounted chips completely immersed for 10±1second in a SAC solder bath at 260°C±5°C	no visible damage Δ R/R max. ±(1%+0.05Ω)
Solderability Clause 4.17	Un-mounted chips completely immersed for 2±0.5 second in a SAC solder bath at 235°C±5°C	good tinning (>95% covered) no visible damage
Temperature cycling Clause 4.19	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +155°C±3°C, 2~3 minutes at 20°C+5°C-1°C, total 5 continuous cycles	no visible damage ΔR/R max. ±(1%+0.05Ω)
Load life (endurance) Clause 4.25	1000 +48/-0 hours, loaded with RCWV or Vmax in chamber controller 70±2°C, 1.5 hours on and 0.5 hours off	ΔR/R max. ±(3%+0.1Ω)
Load life in Humidity Clause 4.24	1000 +48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at 40°C±2°C and 90~95% relative humidity, 1.5hours on and 0.5 hours off	ΔR/R max. ±(3%+0.1Ω)
Bending strength Clause 4.33	Resistors mounted on a 90mm glass epoxy resin PCB(FR4); bending : 2 mm, once for 10 seconds	ΔR/R max. ±(1%+0.05Ω)
Adhesion Clause 4.32	Pressurizing force: 5N, Test time: 10±1sec.	No remarkable damage or removal of the terminations
Insulation Resistance Clause 4.6	Apply the maximum overload voltage (DC) for 1minute	R ≥ 10GΩ
Dielectric Withstand Voltage Clause 4.7	Apply the maximum overload voltage (AC) for 1 minute	No breakdown or flashover

8. PACKAGING

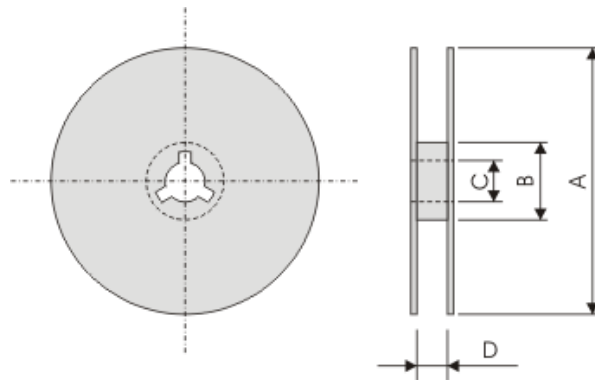
8.1 Plastic Tape specifications (unit :mm)



Type	A	B	W	F	E
CRA8	4.90±0.20	3.55±0.30	12.00±0.30	5.50±0.10	1.75±0.10
CROA	5.50±0.20	2.80±0.20			
CR12	6.90±0.20	3.60±0.20			

Type	P1	P0	ΦD	T
CRA8	8.00±0.10	4.00±0.10	Φ1.50 ^{+0.1} _{-0.0}	1.30±0.20
CROA	4.00±0.10			MAX1.2
CR12				

8.2 Reel dimensions



(unit : mm)

Symbol	A	B	C	D
7" Reel	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	12.4.0±1.00
10" Reel	Φ254.0±2.0	Φ100.0±1.0	13.0±0.2	14.0±0.20
13" Reel	Φ330.0±2.0	Φ100.0±1.0	13.0±0.2	14.0±0.20

8.3 Taping Quantity:

Tape	Paper Tape						Embossed Tape	Bulk Cassette
	4mm pitch			2mm pitch			4mm pitch	
	7"	10"	13"	7"	10"	13"	7"	
1218	-	-	-	3000	3000	-	-	-
2010	-	-	-	4000	8000	16000	-	-
2512	-	-	-	4000	8000	16000	-	-

9. Performance of Taping :

9.1. Strength of Carrier Tape and Top Cover Tape

-Carrier Tape

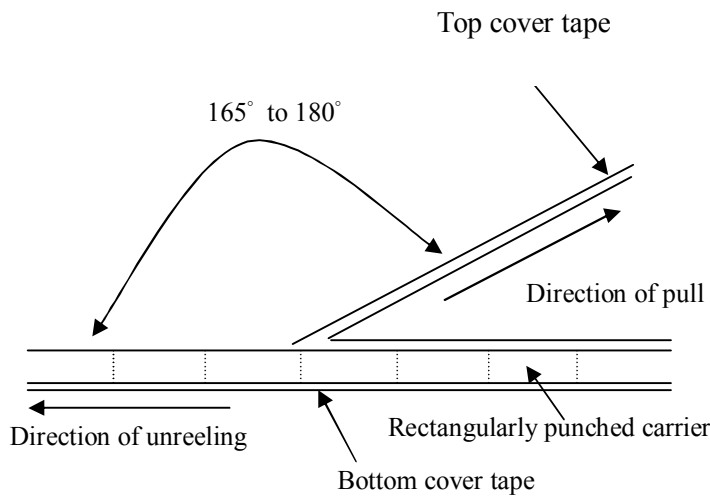
When a tensile force 1.02kgf is applied in the direction of unreeling the tape, the tape shall withstand this force.

-Top cover Tape

When a tensile force 1.02kgf is applied to the tape, the tape shall withstand this force.

9.2 Peel Force of Top Cover Tape

Unless otherwise specified, the peel force of top cover tape shall be 10.2 to 71.4 g f when the top cover tape is pulled at a speed of 300mm/min with the angle between the taped during peel and the direction of unreeling maintained at 165 to 180° as illustrated in Fig.



10. Resistance Marking Explanation:

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

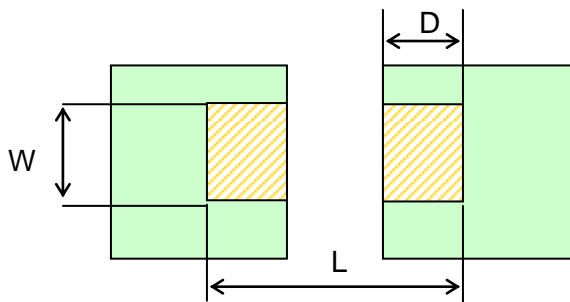
Example:

$$1R00 = 1\Omega$$

$$1001 = 1000\Omega$$

$$0000 = 0\Omega$$

11. Recommended Solder Pad Dimensions



Type	W (mm)	L (mm)	D (mm)
01(0201)	0.25~0.3	0.7~0.9	0.3~0.4
02(0402)	0.5~0.6	1.4~1.6	0.4~0.6
03(0603)	0.7~0.9	2.0~2.2	0.8~1.0
05(0805)	1.0~1.4	3.2~3.8	0.9~1.4
06(1206)	2.0~2.4	4.4~5.0	1.2~1.8
10(1210)	2.0~2.4	4.4~5.0	2.3~3.5
0A(2010)	3.3~3.7	5.7~6.5	2.3~3.5
12(2512)	3.6~4.0	7.8~8.6	2.3~3.5

Note :

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.